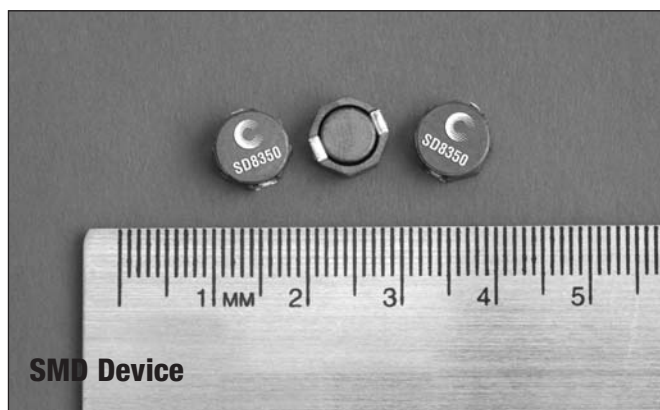


Shielded Power Inductors

SD8350 Series



Description

- Halogen free, lead free
- 125°C maximum total temperature operation
- Low-profile surface mount inductor
- 9.5 x 8.3 x 4.5mm shielded drum core
- Ferrite core material
- Inductance range from 1.5μH to 100μH
- Current range from 0.8 Amps to 9.1 Amps
- Frequency range up to 1MHz
- RoHS Compliant

Applications

- Server/notebook power
- High power LED driver, portable devices
- Base station, telecom, and networking
- Battery chargers, RAM power supply
- Industrial and automotive power systems
- Noise filtering output filter chokes
- Buck/boost converters, output converters

Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant

Packaging

- Supplied in tape and reel packaging, 750 parts per 13 inch dia. reel

Product Specifications							
Part Number	Rated Inductance (μH)	OC ¹ μH±30%	I _{rms} ² (Amps)	I _{sat} ³ (Amps)	DCR mΩ @ 20°C Typical	DCR mΩ @ 20°C Maximum	K-factor ⁴
SD8350-1R8-R	1.8	1.5	5.50	9.1	11.8	14.0	16.0
SD8350-3R9-R	3.9	3.2	4.50	6.3	16.2	19.0	9.6
SD8350-4R7-R	4.7	4.2	4.10	5.5	18.5	22.0	8.5
SD8350-6R8-R	6.8	6.8	3.90	4.4	20.8	25.0	7.6
SD8350-100-R	10	9.9	3.20	4.0	31.4	36.0	6.3
SD8350-150-R	15	13.6	2.30	2.9	45.0	53.0	5.3
SD8350-220-R	22	20.4	1.80	2.6	63.5	75.0	4.4
SD8350-330-R	33	31.4	1.40	2.2	111.4	125.0	3.5
SD8350-470-R	47	44.9	1.30	1.8	130.0	150.0	2.9
SD8350-680-R	68	65.1	1.00	1.5	200.8	240.0	2.4
SD8350-101-R	100	99.7	0.80	1.3	308.0	360.0	2.0

1. Open Circuit Inductance Test Parameters: 100kHz, 0.1V, 0.0Adc.

2. I_{rms}: DC current for an approximate ΔT of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

3. I_{sat}: Amps peak for approximately 35% rolloff (@25°C)

4. K-factor: Used to determine B_{p-p} for core loss (see graph).

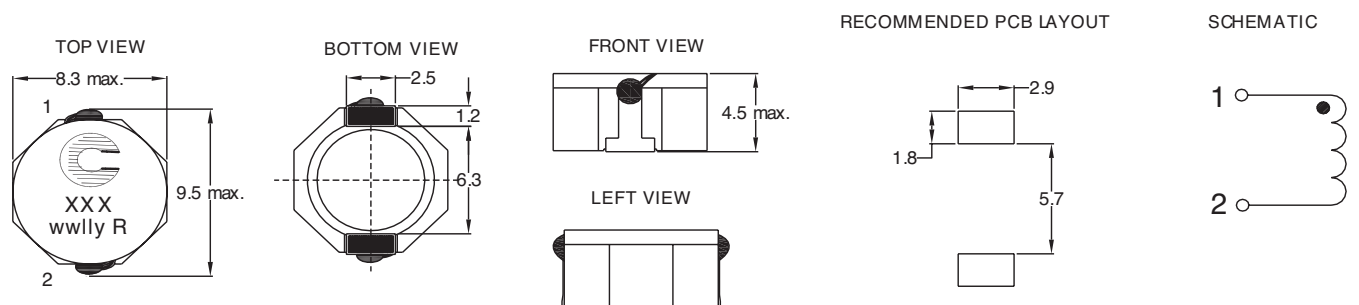
B_{p-p} = K*L*ΔI, B_{p-p} (mT), K: (K factor from table), L: (Inductance in μH), ΔI (Peak to peak ripple current in Amps).

5. Part Number Definition: SD8350-xxx-R

SD8350 = Product code and size; -xxx = Inductance value in μH; R = decimal point; If no R is present, third character = # of zeros.

-R suffix = RoHS compliant

Dimensions - mm



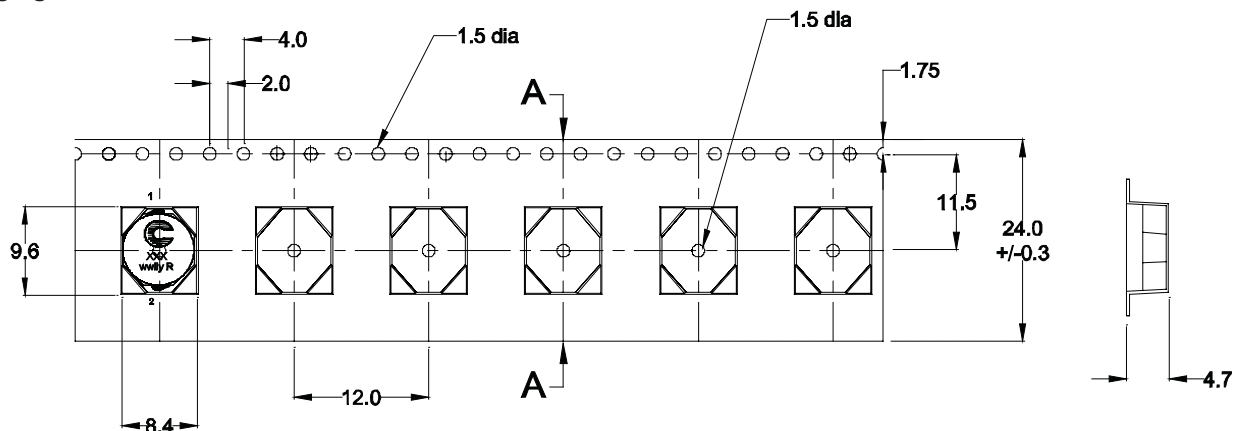
Part Marking: Coiltronics logo

xxx = Inductance value in μH . (R = Decimal point). If no R is present, third character = number of zeros

wwly - or - wwlyly = Date code

R = Revision level

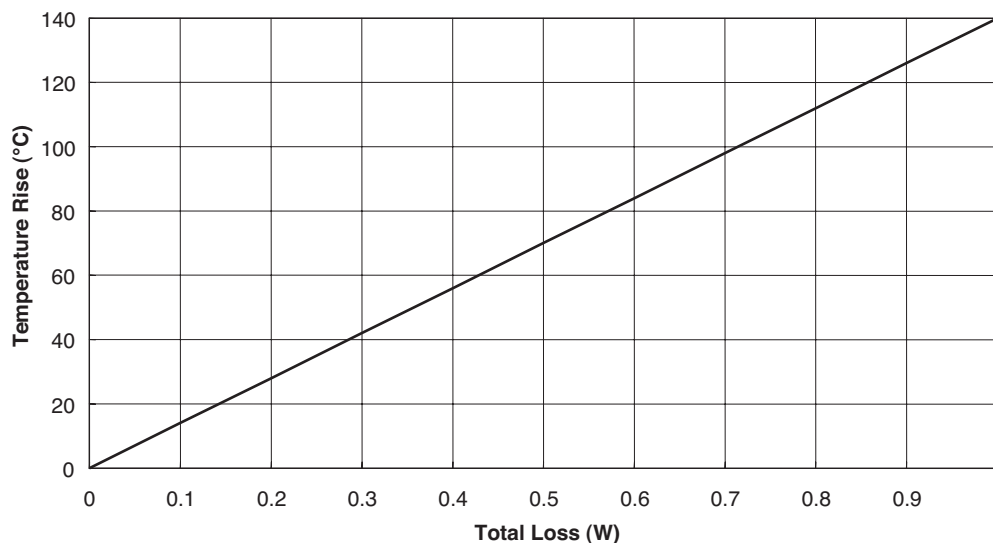
Packaging Information - mm



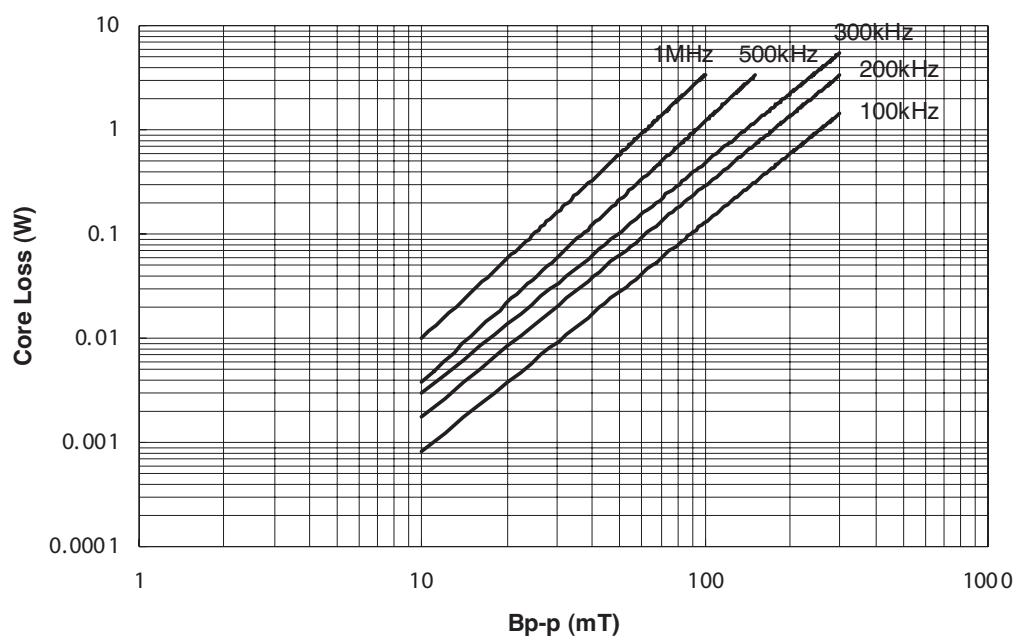
Supplied in tape-and-reel packaging, 750 parts per reel, 13" diameter reel.

SECTION A-A

Temperature Rise vs.Total Loss

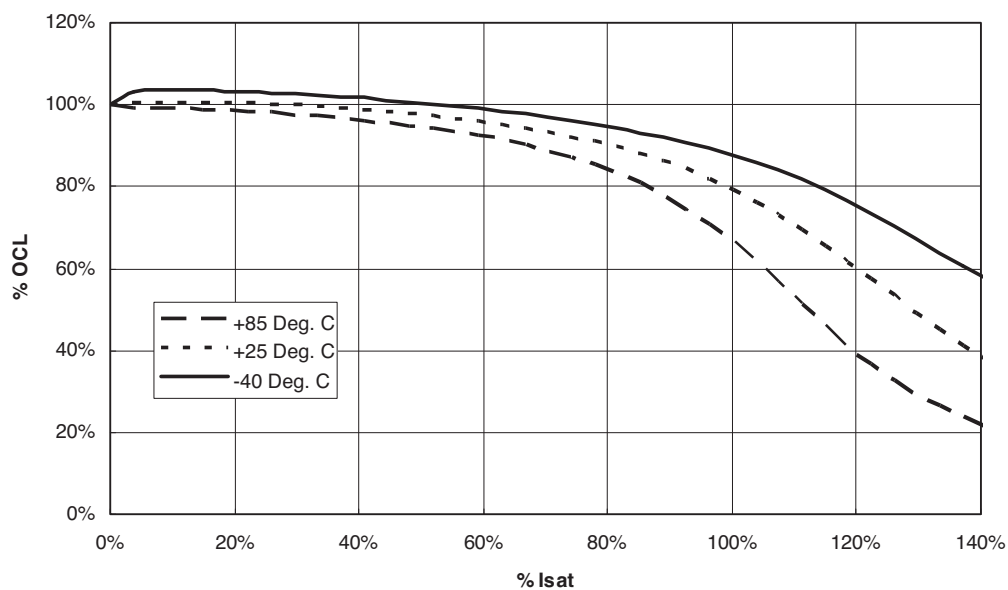


Core Loss



Inductance Characteristics

OCL Vs. Isat



Solder Reflow Profile

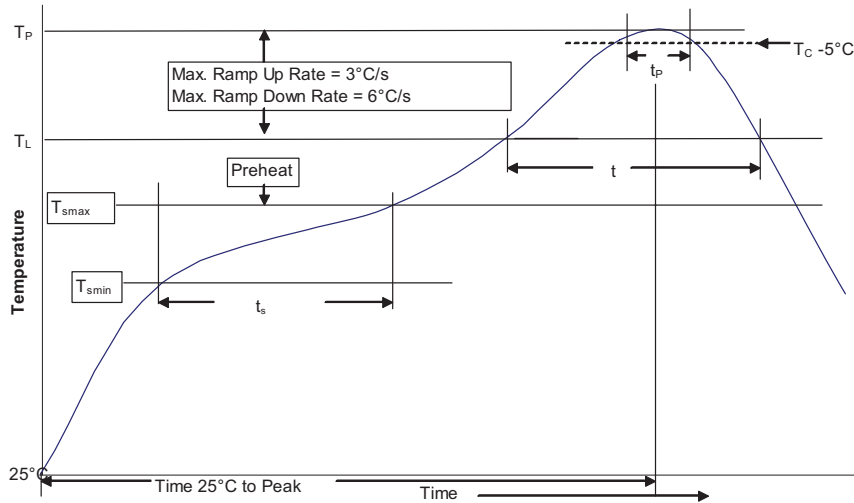


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_P	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_P to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

North America

Cooper Electronic Technologies
1225 Broken Sound Parkway NW
Suite F
Boca Raton, FL 33487-3533
Tel: 1-561-998-4100
Fax: 1-561-241-6640
Toll Free: 1-888-414-2645

Cooper Bussmann
P.O. Box 14460
St. Louis, MO 63178-4460
Tel: 1-636-394-2877
Fax: 1-636-527-1607

Europe

Cooper Electronic Technologies
Cooper (UK) Limited
Burton-on-the-Wolds
Leicestershire • LE12 5TH UK
Tel: +44 (0) 1509 882 737
Fax: +44 (0) 1509 882 786

Cooper Electronic Technologies
Avda. Santa Eulalia, 290
08223
Terrassa, (Barcelona), Spain
Tel: +34 937 362 812
+34 937 362 813
Fax: +34 937 362 719

Asia Pacific

Cooper Electronic Technologies
1 Jalan Kilang Timor
#06-01 Pacific Tech Centre
Singapore 159303
Tel: +65 278 6151
Fax: +65 270 4160

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9